

Legacy NAND Flash Part Numbering System

Micron's part numbering system is available at www.micron.com/support/designsupport/documents/png

Legacy NAND Flash*

MT

29F

2G

08

A

A

A

WP

-

xx

xx

xx

xx

ES

:

A

Micron Technology

Single-Supply Flash

Density

Device Width

Classification

29F = NAND Flash

29H = High Speed NAND

1G = 1Gb

2G = 2Gb

4G = 4Gb

8G = 8Gb

16G = 16Gb

32G = 32Gb

64G = 64Gb

128G = 128Gb

256G = 256Gb

08 = 8 bits

16 = 16 bits

Mark	Die	nCE	RnB	I/O Channels
A	1	0	0	1
B	1	1	1	1
D	2	1	1	1
E	2	2	2	2
F	2	2	2	1
G	3	3	3	3
J	4	2	2	1
K	4	2	2	2
L	4	4	4	4
M	4	4	4	2
Q	8	4	4	4
R	8	2	2	2
T	16	8	4	2
U	8	4	4	2
V	16	8	4	4

Operating Voltage Range

A = 3.3V (2.70–3.60V), VccQ 3.3V (2.70–3.60V)

B = 1.8V (1.70–1.95V)

C = 3.3V (2.70–3.60V), VccQ 1.8V (1.70–1.95V)

Design Revision (shrink)

A = 1st design revision

Production Status

Blank = Production

ES = Engineering samples

QS = Qualification samples

MS = Mechanical samples

Operating Temperature Range

Blank = Commercial (0°C to +70°C)

ET = Extended (–40°C to +85°C)

WT = Wireless (–25°C to +85°C)

Block Option (Reserved for use)

Blank = Standard device

Flash Performance

Blank = Full specification

Speed Grade (MT29H Only)

15 = 133 MT/s

12 = 166 MT/s

Package Code (dimensions in mm)

WP = 48-pin TSOP I (CPL version) (Pb-free)

WC = 48-pin TSOP I (OCPL version) (Pb-free)

H1 = 100-ball VFBGA (Pb-free), 12 x 18 x 1.0

H2 = 100-ball TFBGA (Pb-free), 12 x 18 x 1.2

HC = 63-ball VFBGA, 10.5 x 13 x 1.0

C2 = 52-pad ULGA, 12 x 17 x 0.4 (use TBD)

C3 = 52-pad ULGA, 12 x 17 x 0.65

C4 = 52-pad VLGA, 12 x 17 x 1.0 (SDP/DDP/QDP)

C5 = 52-pad VLGA, 14 x 18 x 1.0 (SDP/DDP/QDP)

C6 = 52-pad LLGA, 14 x 18 x 1.47 (8DP, QDP, DDP)

C7 = 48-pad LLGA, 12 x 20 x 1.47 (8DP)

SWC = 48-pin Stacked TSOP (OCPL version) (Pb-free)

SWP = 48-pin Stacked TSOP (CPL version) (Pb-free)

Generation (M29 only)/Feature Set

A = 1st set of device features

B = 2nd set of device features (rev only if different than 1st set)

C = 3rd set of device features (rev only if different)

D = 4th set of device features (rev onl H4 = 63-ball VFBGA, 9 x 11 x 1.0 etc.

*This numbering system is no longer used for Micron NAND flash. See the NAND Part Numbering System for the modern numbering guide.

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